

In re Patent Application of:

**YOUNG ET AL.**

Serial No. 10/083,794

Filed: **FEBRUARY 27, 2002**

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**IN THE CLAIMS**

1. (currently amended) A method of removing an optical device contained within a device package from a circuit board, wherein the device package is secured to the circuit board using an adhesive pad positioned between the device package and the circuit board, and wherein the optical device includes one or more leads extending outwardly therefrom into close proximity with the circuit board for soldering thereto, the method comprising:

a) peeling a portion of the adhesive pad away from the circuit board;

b) inserting an optical removal tool between the optical device and the circuit board, wherein the optical removal tool has a pair of fork portions extending from a handle and a cavity positioned between the fork portions, and the fork portions straddle one or more of the leads on the optical device during ~~the inserting~~ step b); and

c) prying the remainder of the adhesive pad away from the circuit board using said optical device removal tool.

2. (original) The method of claim 1, wherein said optical device further includes electric lead interconnects soldered to electric connections on the circuit board, the method further comprising breaking the soldered connections.

3. (original) The method of claim 2, wherein the breaking the soldered connections is performed by heating the soldered connections to a temperature above a temperature at which the solder of the soldered connections melt, but below a temperature that is likely to do any thermal damage to the optical device.

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4. (original) The method of claim 1, further comprising:  
removing the adhesive pad from the device package.

5. Cancel

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7. Cancel

8. (new) The method of claim 1, wherein step a) includes peeling a portion of the adhesive pad away from the circuit board using a peeling blade extending from one of the fork portions of the optical removal tool.

9. (new) The method of claim 8, wherein step c) includes pivoting said optical removal tool about a pivot point between said fork portions and said handle.

10. (new) The method of claim 9, wherein the fork portions are perpendicular to said handle.